

# PIN diode

## RN731V

### ●Applications

VHF / UHF band variable attenuators and AGC

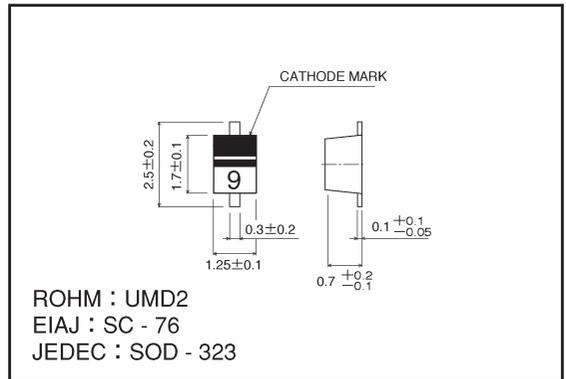
### ●Features

- 1) Small surface mounting type. (UMD2)
- 2) Low high-frequency forward resistance ( $r_F$ ) / low capacitance ( $C_T$ ).
- 3) High reliability.

### ●Construction

Silicon diffusion junction

### ●External dimensions (Units: mm)



### ●Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Limits	Unit
DC reverse voltage	$V_R$	50	V
DC forward current	$I_F$	50	mA
Power dissipation	$P_d$	100	mW
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	$-55 \sim +125$	$^\circ\text{C}$

### ●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	$V_F$	—	0.93	1.0	V	$I_F = 50\text{mA}$
Reverse current	$I_R$	—	0.01	100	nA	$V_R = 50\text{V}$
Capacitance between terminals	$C_T$	—	0.23	0.4	pF	$V_R = 35\text{V}$ , $f = 1\text{MHz}$
Forward operating resistance	$r_F$	—	3.5	7	$\Omega$	$I_F = 10\text{mA}$ , $f = 100\text{MHz}$

●Electrical characteristic curves (Ta = 25°C unless specified otherwise)

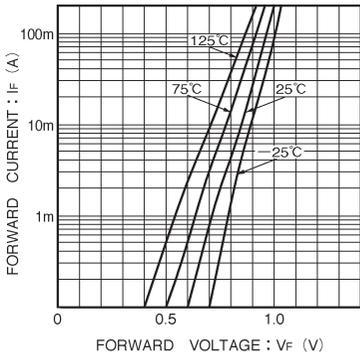


Fig. 1 Forward characteristics

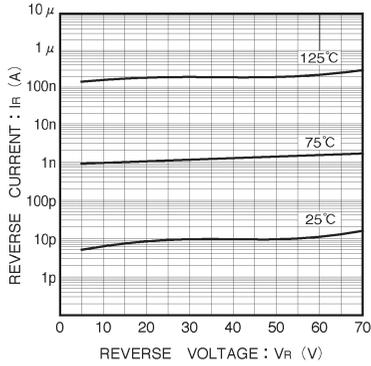


Fig. 2 Reverse characteristics

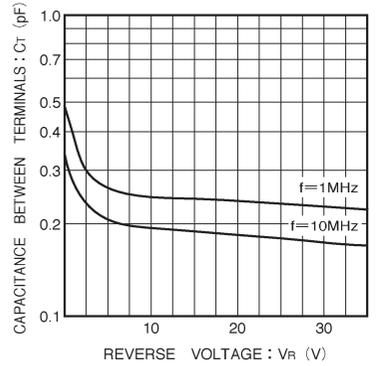


Fig. 3 Capacitance between terminals characteristics ( I )

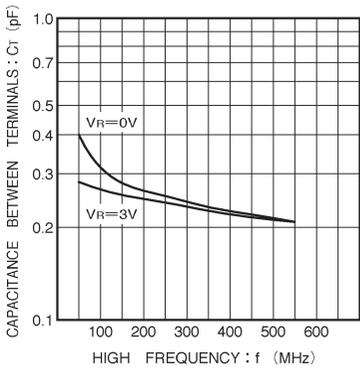


Fig. 4 Capacitance between terminals characteristics ( II )

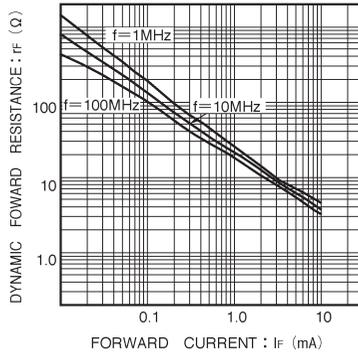


Fig. 5 High frequency characteristics

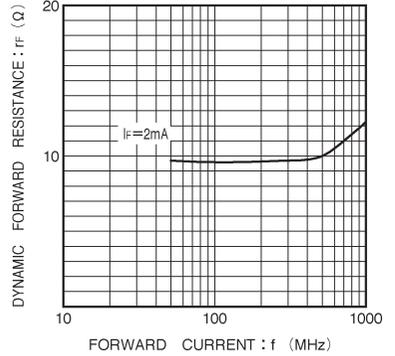


Fig. 6 Forward operating resistance characteristics

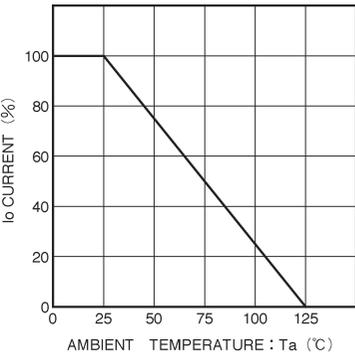


Fig. 7 Derating curve (mounting on glass epoxy PCBs)